

IRG7PH42U-EP Datasheet



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	IRG7PH42U-EP-DG
Manufacturer	Infineon Technologies
Manufacturer Product Number	IRG7PH42U-EP
Description	IGBT 1200V 90A 385W TO247AD
Detailed Description	IGBT Trench 1200 V 90 A 385 W Through Hole TO-247AD



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

IRG7PH42U-EP

Series:

-

IGBT Type:

Trench

Current - Collector (Ic) (Max):

90 A

Vce(on) (Max) @ Vge, Ic:

2V @ 15V, 30A

Switching Energy:

2.11mj (on), 1.18mj (off)

Gate Charge:

157 nC

Test Condition:

600V, 30A, 100hm, 15V

Operating Temperature:

-55°C ~ 175°C (Tj)

Package / Case:

TO-247-3

Base Product Number:

IRG7PH42

Manufacturer:

Infineon Technologies

Product Status:

Obsolete

Voltage - Collector Emitter Breakdown (Max):

1200 V

Current - Collector Pulsed (Icm):

90 A

Power - Max:

385 W

Input Type:

Standard

Td (on/off) @ 25°C:

25ns/229ns

Reverse Recovery Time (trr):

153 ns

Mounting Type:

Through Hole

Supplier Device Package:

TO-247AD

Environmental & Export classification

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

REACH Status:

REACH Unaffected

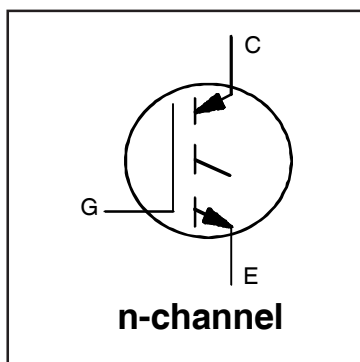
HTSUS:

8541.29.0095

INSULATED GATE BIPOLAR TRANSISTOR

Features

- Low $V_{CE(ON)}$ trench IGBT technology
- Low switching losses
- Maximum junction temperature 175 °C
- Square RBSOA
- 100% of the parts tested for I_{LM}
- Positive $V_{CE(ON)}$ temperature co-efficient
- Tight parameter distribution
- Lead-Free



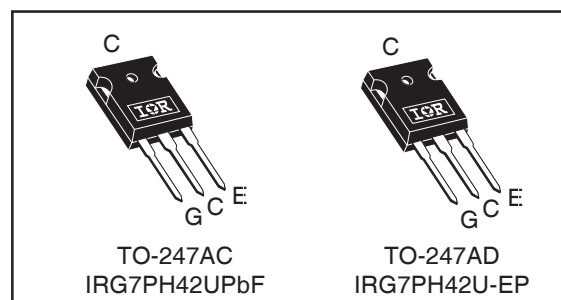
$V_{CES} = 1200V$
 $I_C = 60A, T_C = 100^\circ C$
 $T_{J(max)} = 175^\circ C$
 $V_{CE(on)} \text{ typ.} = 1.7V$

Benefits

- High efficiency in a wide range of applications
- Suitable for a wide range of switching frequencies due to low $V_{CE(ON)}$ and low switching losses
- Rugged transient performance for increased reliability
- Excellent current sharing in parallel operation

Applications

- U.P.S
- Welding
- Solar inverter
- Induction heating



G	C	E
Gate	Collector	Emitter

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	1200	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current (Silicon Limited)	90 ^④	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current (Silicon Limited)	60	
$I_{NOMINAL}$	Nominal Current	30	
I_{CM}	Pulse Collector Current, $V_{GE} = 15V$	90	
I_{LM}	Clamped Inductive Load Current, $V_{GE} = 20V$ ①	120	
V_{GE}	Continuous Gate-to-Emitter Voltage	± 30	V
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	385	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	192	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +175	°C
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw	10 lbf-in (1.1 N·m)	

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$ (IGBT)	Thermal Resistance Junction-to-Case-(each IGBT) TO-247AC ④	—	—	0.39	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink (flat, greased surface) ④	—	0.24	—	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (typical socket mount)	—	40	—	

IRG7PH42UPbF/IRG7PH42U-EP

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	1200	—	—	V	$V_{GE} = 0V, I_C = 100\mu\text{A}$ ③
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	1.2	—	V/°C	$V_{GE} = 0V, I_C = 1\text{mA}$ (25°C-150°C) ③
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	—	1.7	2.0	V	$I_C = 30\text{A}, V_{GE} = 15V, T_J = 25^\circ\text{C}$ ②
		—	2.1	—		$I_C = 30\text{A}, V_{GE} = 15V, T_J = 150^\circ\text{C}$ ②
		—	2.2	—		$I_C = 30\text{A}, V_{GE} = 15V, T_J = 175^\circ\text{C}$ ②
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	6.0	V	$V_{CE} = V_{GE}, I_C = 1\text{mA}$
$\Delta V_{GE(th)}/\Delta T_J$	Threshold Voltage temp. coefficient	—	-16	—	mV/°C	$V_{CE} = V_{GE}, I_C = 1\text{mA}$ (25°C - 175°C)
g_{fe}	Forward Transconductance	—	32	—	S	$V_{CE} = 50V, I_C = 30\text{A}, PW = 80\mu\text{s}$
I_{CES}	Collector-to-Emitter Leakage Current	—	1	150	μA	$V_{GE} = 0V, V_{CE} = 1200V$
		—	700	—		$V_{GE} = 0V, V_{CE} = 1200V, T_J = 175^\circ\text{C}$
I_{GES}	Gate-to-Emitter Leakage Current	—	—	± 100	nA	$V_{GE} = \pm 20V$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	—	157	236	nC	$I_C = 30\text{A}$ ② $V_{GE} = 15V$ $V_{CC} = 600V$
Q_{ge}	Gate-to-Emitter Charge (turn-on)	—	21	32		
Q_{gc}	Gate-to-Collector Charge (turn-on)	—	69	104		
E_{on}	Turn-On Switching Loss	—	2105	2374	μJ	$I_C = 30\text{A}, V_{CC} = 600V, V_{GE} = 15V$ ② $R_G = 10\Omega, L = 200\mu\text{H}, T_J = 25^\circ\text{C}$ Energy losses include tail & diode reverse recovery Diode clamp the same as IRG7PH42UDPbF
E_{off}	Turn-Off Switching Loss	—	1182	1424		
E_{total}	Total Switching Loss	—	3287	3798		
$t_{d(on)}$	Turn-On delay time	—	25	34	ns	Diode clamp the same as IRG7PH42UDPbF
t_r	Rise time	—	32	41		
$t_{d(off)}$	Turn-Off delay time	—	229	271		
t_f	Fall time	—	63	86		
E_{on}	Turn-On Switching Loss	—	3186	—	μJ	$I_C = 30\text{A}, V_{CC} = 600V, V_{GE} = 15V$ ② $R_G = 10\Omega, L = 200\mu\text{H}, T_J = 175^\circ\text{C}$ Energy losses include tail & diode reverse recovery Diode clamp the same as IRG7PH42UDPbF
E_{off}	Turn-Off Switching Loss	—	2153	—		
E_{total}	Total Switching Loss	—	5339	—		
$t_{d(on)}$	Turn-On delay time	—	20	—	ns	Diode clamp the same as IRG7PH42UDPbF
t_r	Rise time	—	31	—		
$t_{d(off)}$	Turn-Off delay time	—	310	—		
t_f	Fall time	—	162	—		
C_{ies}	Input Capacitance	—	3338	—	pF	$V_{GE} = 0V$ $V_{CC} = 30V$ $f = 1.0\text{MHz}$
C_{oes}	Output Capacitance	—	124	—		
C_{res}	Reverse Transfer Capacitance	—	75	—		
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				$I_C = 120\text{A}$ $V_{CC} = 960V, V_p = 1200V$ $R_G = 10\Omega, V_{GE} = +20V \text{ to } 0V, T_J = 175^\circ\text{C}$

Notes:

- ① $V_{CC} = 80\% (V_{CES}), V_{GE} = 20V, L = 22\mu\text{H}, R_G = 10\Omega$
- ② Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- ③ Refer to AN-1086 for guidelines for measuring $V_{(BR)CES}$ safely.
- ④ R_θ is measured at T_J of approximately 90°C .
- ⑤ Calculated continuous current based on maximum allowable junction temperature. Bond wire current limit is 78A. Note that current limitations arising from heating of the device leads may occur with some lead mounting arrangements.

IRG7PH42UPbF/IRG7PH42U-EP

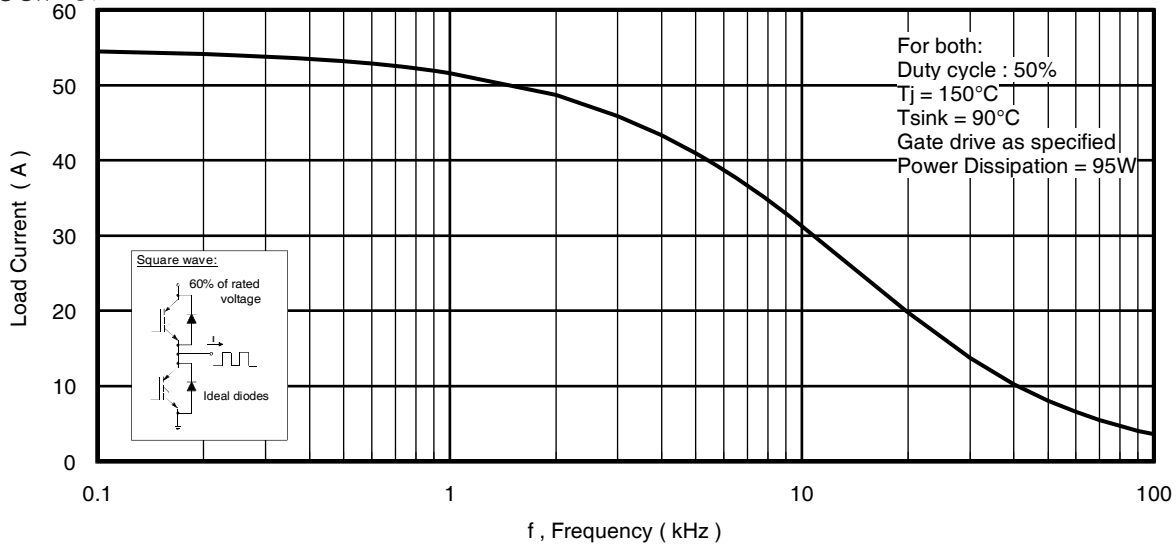


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

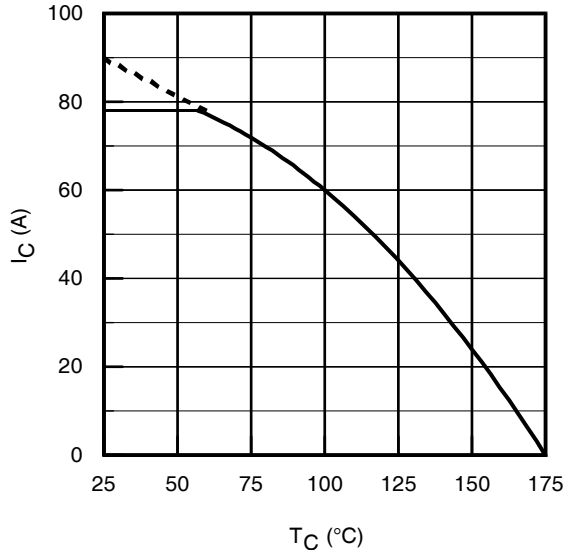


Fig. 2 - Maximum DC Collector Current vs. Case Temperature

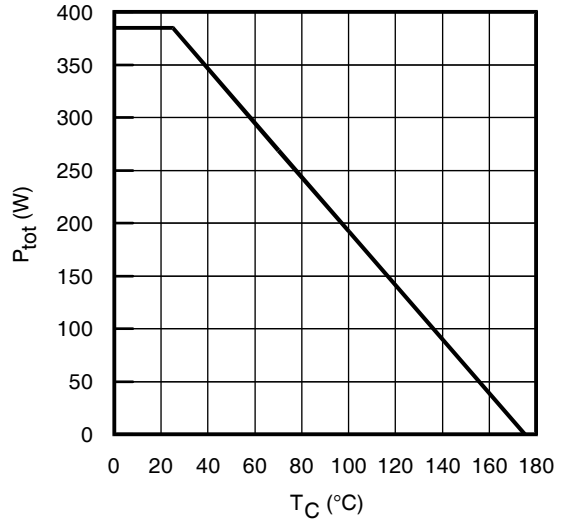


Fig. 3 - Power Dissipation vs. Case Temperature

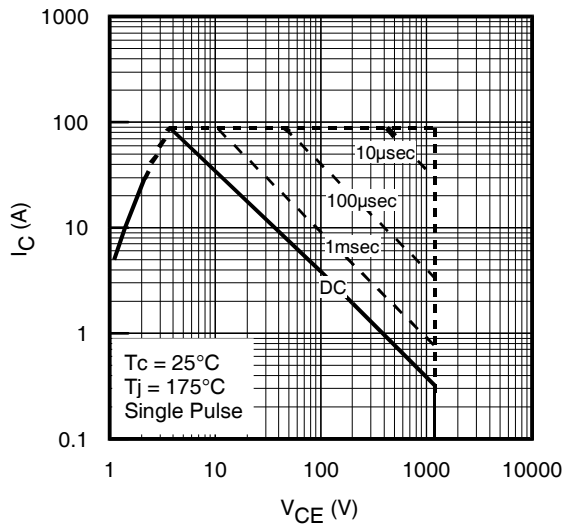


Fig. 4 - Forward SOA
 $T_C = 25^\circ\text{C}, T_J \leq 175^\circ\text{C}; V_{GE} = 15\text{V}$

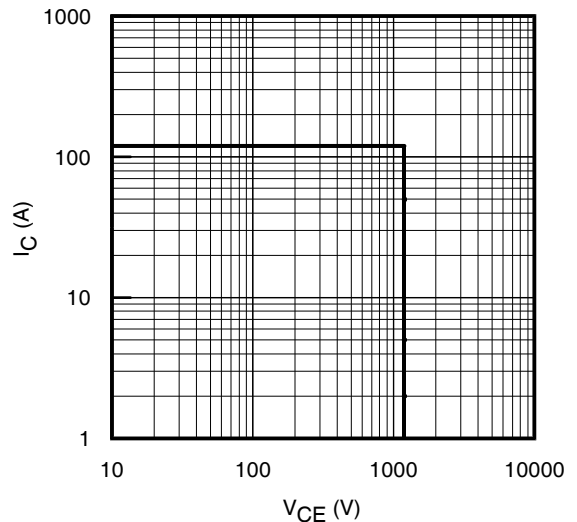


Fig. 5 - Reverse Bias SOA
 $T_J = 175^\circ\text{C}; V_{GE} = 20\text{V}$

IRG7PH42UPbF/IRG7PH42U-EP

International
IR Rectifier

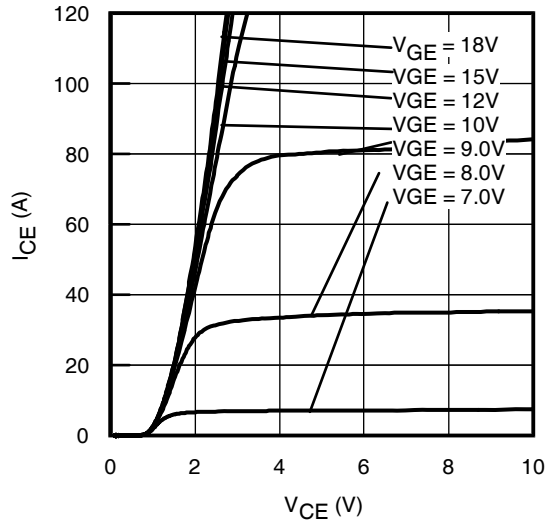


Fig. 6 - Typ. IGBT Output Characteristics
 $T_J = -40^\circ\text{C}$; $t_p = 20\mu\text{s}$

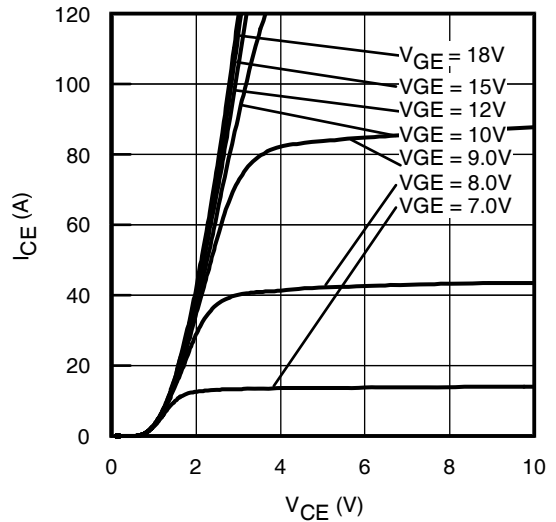


Fig. 7 - Typ. IGBT Output Characteristics
 $T_J = 25^\circ\text{C}$; $t_p = 20\mu\text{s}$

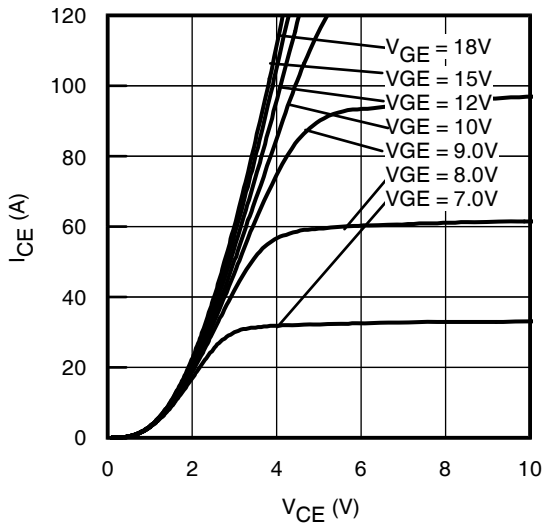


Fig. 8 - Typ. IGBT Output Characteristics
 $T_J = 175^\circ\text{C}$; $t_p = 20\mu\text{s}$

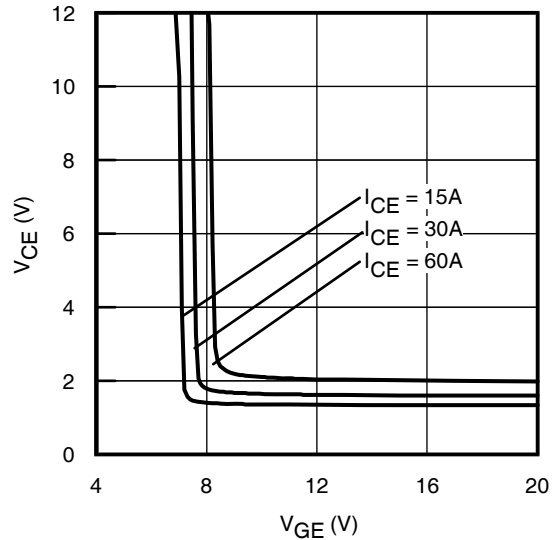


Fig. 9 - Typical V_{CE} vs. V_{GE}
 $T_J = -40^\circ\text{C}$

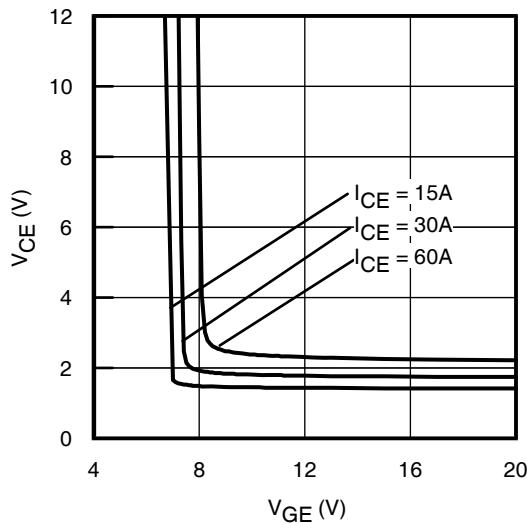


Fig. 10 - Typical V_{CE} vs. V_{GE}
 $T_J = 25^\circ\text{C}$

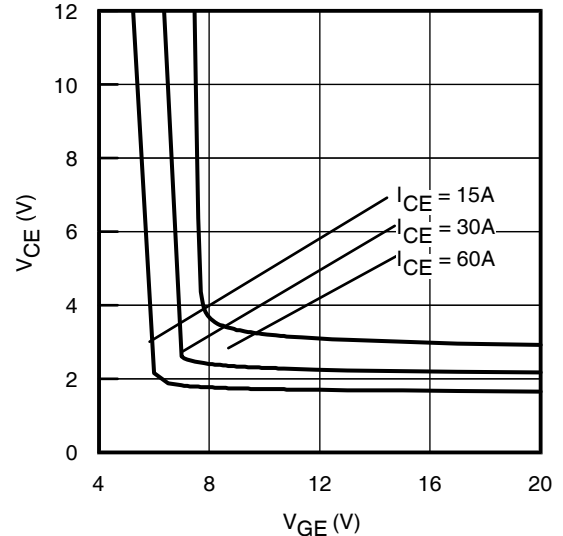


Fig. 11 - Typical V_{CE} vs. V_{GE}
 $T_J = 175^\circ\text{C}$

IRG7PH42UPbF/IRG7PH42U-EP

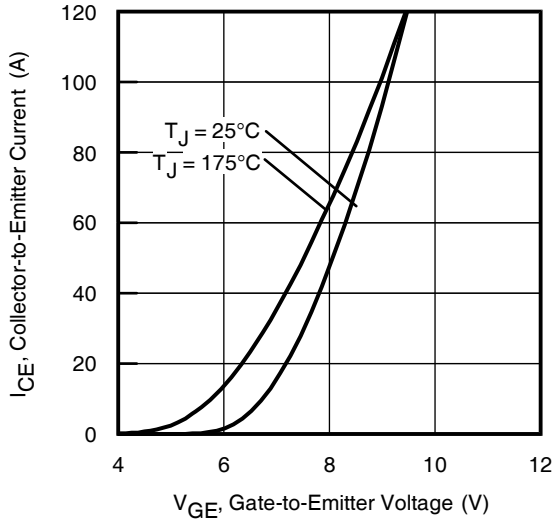


Fig. 12 - Typ. Transfer Characteristics
 $V_{CE} = 50V$; $t_p = 20\mu s$

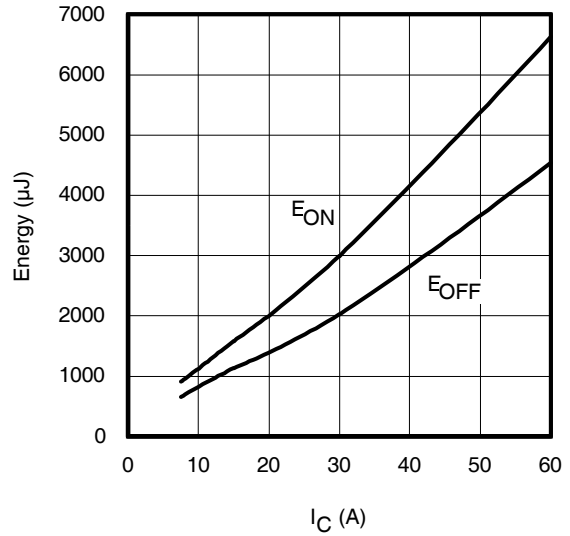


Fig. 13 - Typ. Energy Loss vs. I_C
 $T_J = 175^\circ C$; $L = 200\mu H$; $V_{CE} = 600V$, $R_G = 10\Omega$; $V_{GE} = 15V$

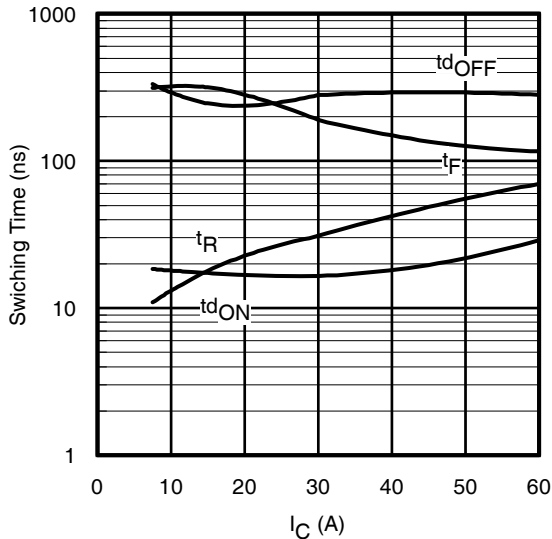


Fig. 14 - Typ. Switching Time vs. I_C
 $T_J = 175^\circ C$; $L = 200\mu H$; $V_{CE} = 600V$, $R_G = 10\Omega$; $V_{GE} = 15V$

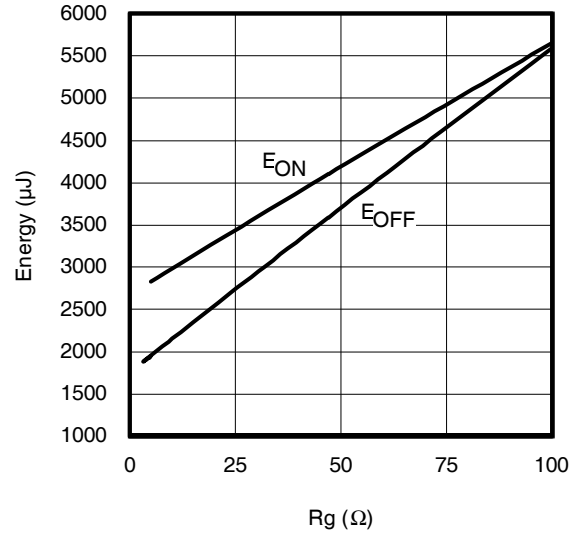


Fig. 15 - Typ. Energy Loss vs. R_G
 $T_J = 175^\circ C$; $L = 200\mu H$; $V_{CE} = 600V$, $I_{CE} = 30A$; $V_{GE} = 15V$

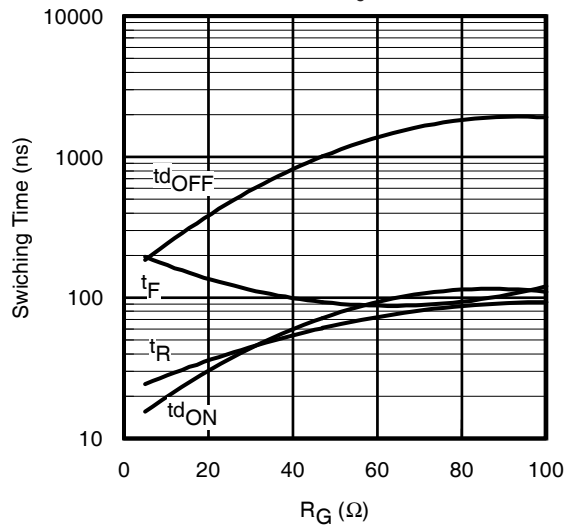


Fig. 16 - Typ. Switching Time vs. R_G
 $T_J = 175^\circ C$; $L = 200\mu H$; $V_{CE} = 600V$, $I_{CE} = 30A$; $V_{GE} = 15V$

IRG7PH42UPbF/IRG7PH42U-EP

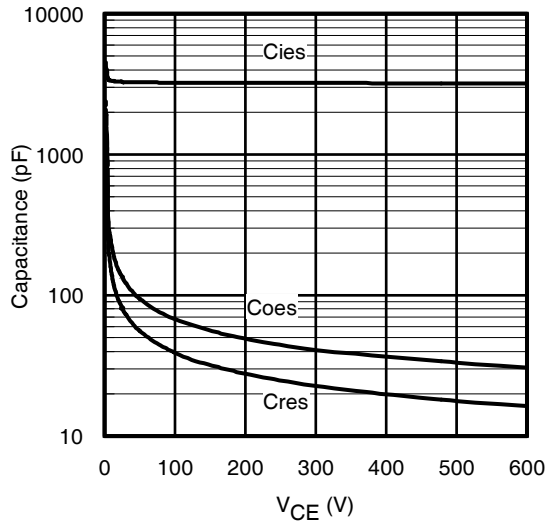


Fig. 17 - Typ. Capacitance vs. V_{CE}
V_{GE} = 0V; f = 1MHz

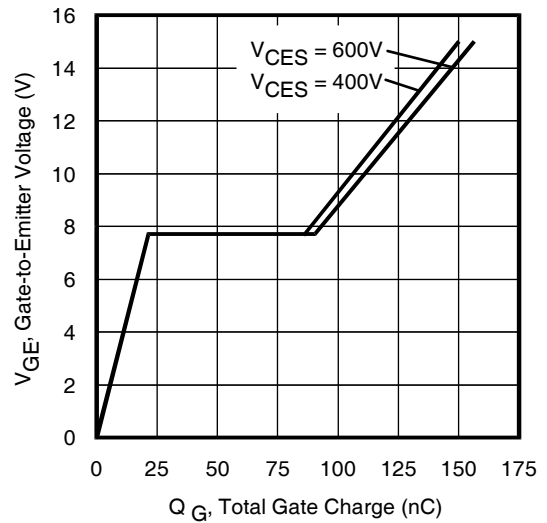


Fig. 18- Typical Gate Charge vs. V_{GE}
I_{CE} = 30A; L = 600μH

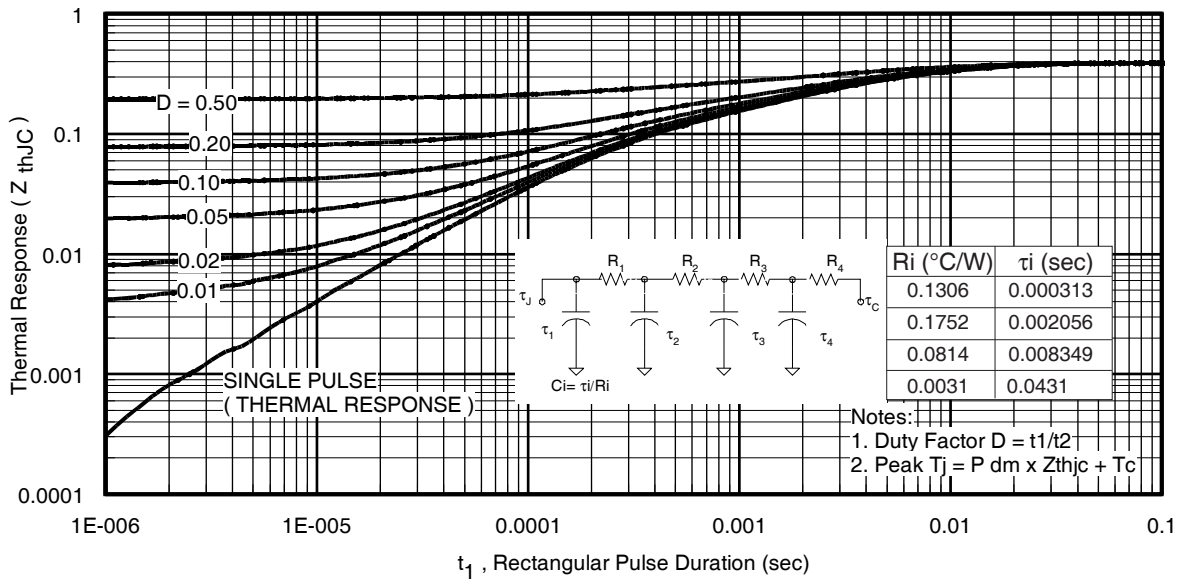


Fig 19. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT) TO-247AC

IRG7PH42UPbF/IRG7PH42U-EP

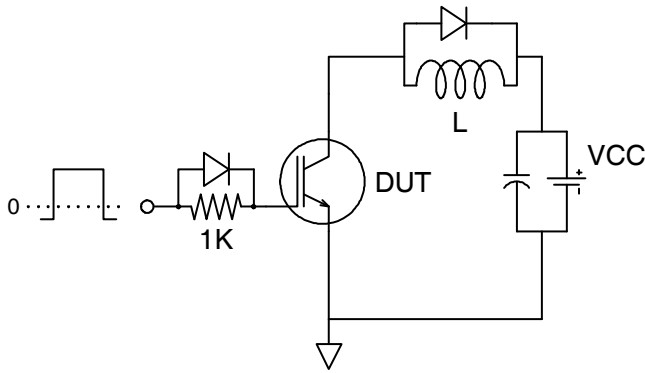


Fig.C.T.1 - Gate Charge Circuit (turn-off)

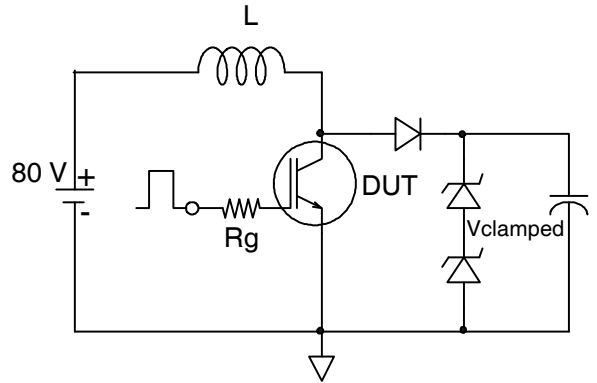


Fig.C.T.2 - RBSOA Circuit

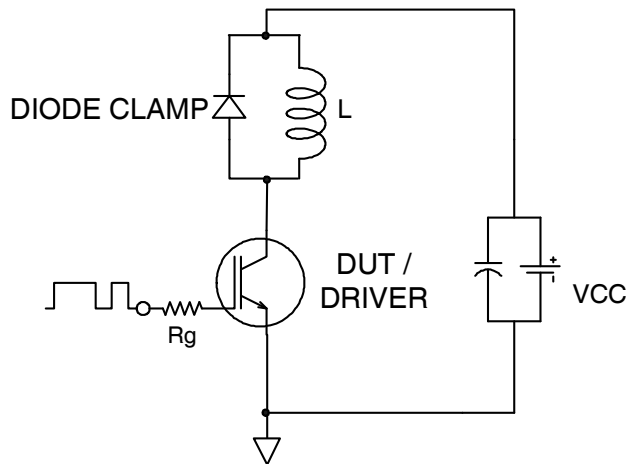


Fig.C.T.3 - Switching Loss Circuit

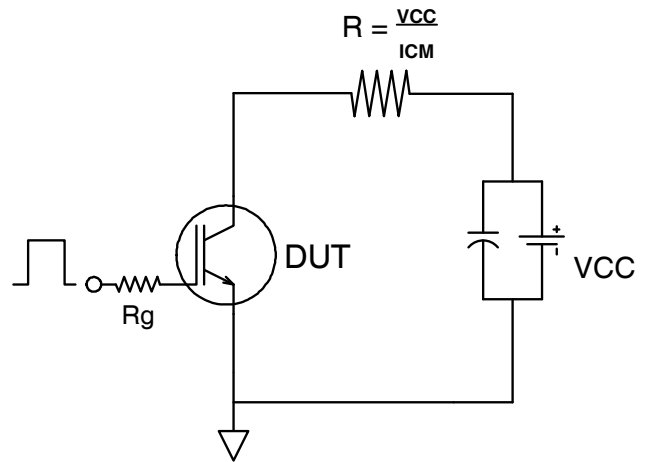


Fig.C.T.4 - Resistive Load Circuit

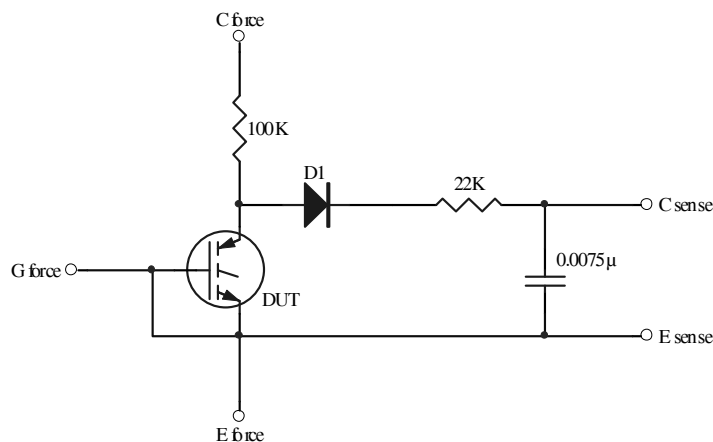


Fig.C.T.5 - BVCES Filter Circuit

IRG7PH42UPbF/IRG7PH42U-EP

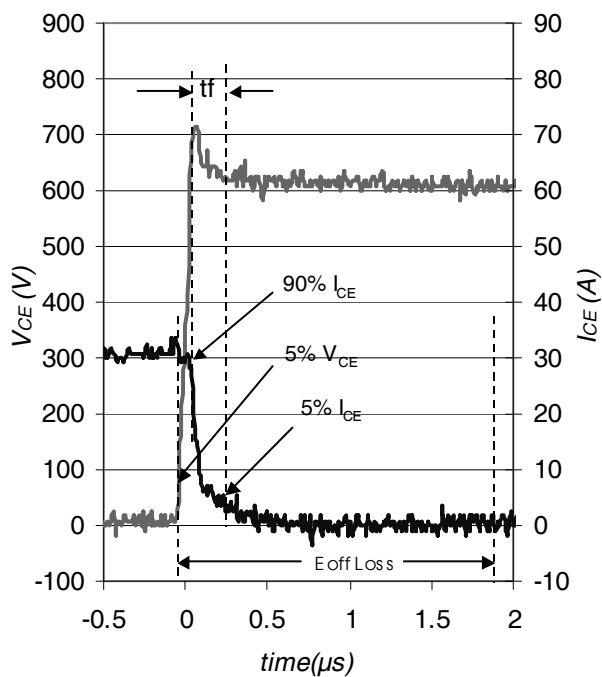


Fig. WF1 - Typ. Turn-off Loss Waveform
@ $T_J = 175^\circ C$ using Fig. CT.4

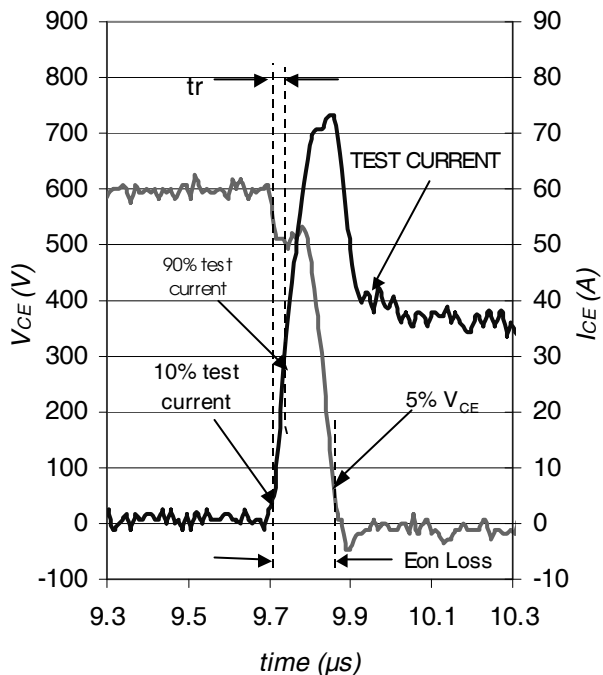
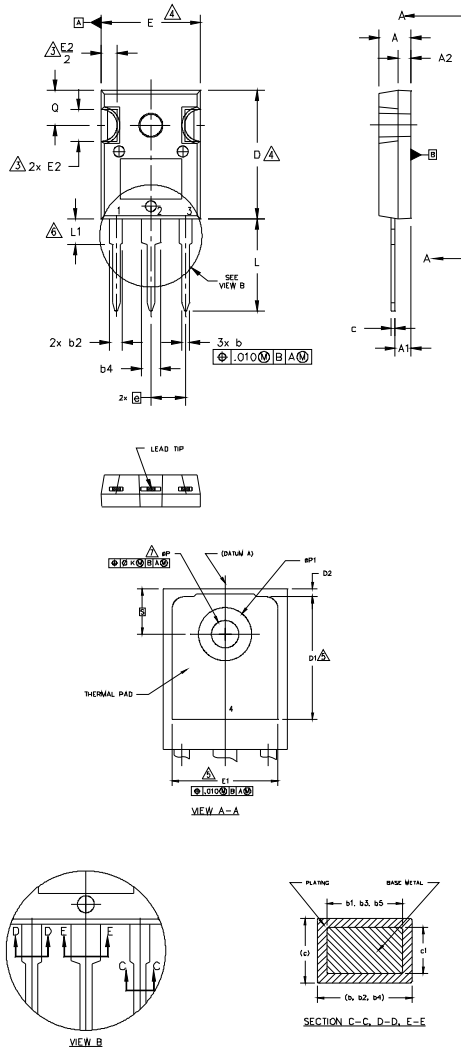


Fig. WF2 - Typ. Turn-on Loss Waveform
@ $T_J = 175^\circ C$ using Fig. CT.4

IRG7PH42UPbF/IRG7PH42U-EP

TO-247AC Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M 1994.
 2. DIMENSIONS ARE SHOWN IN INCHES.
 3. CONTOUR OF SLOT OPTIONAL.
 4. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 5. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS D1 & E1.
 6. LEAD FINISH UNCONTROLLED IN L1.
 7. ØP TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5 ° TO THE TOP OF THE PART WITH A MAXIMUM HOLE DIAMETER OF .154 INCH.
- B. OUTLINE CONFORMS TO JEDEC OUTLINE TO-247AC .

SYMBOL	DIMENSIONS				NOTES
	INCHES		MILLIMETERS		
	MIN.	MAX.	MIN.	MAX.	
A	.183	.209	4.65	5.31	
A1	.087	.102	2.21	2.59	
A2	.059	.098	1.50	2.49	
b	.039	.055	0.99	1.40	
b1	.039	.053	0.99	1.35	
b2	.065	.094	1.65	2.39	
b3	.065	.092	1.65	2.34	
b4	.102	.135	2.59	3.43	
b5	.102	.133	2.59	3.38	
c	.015	.035	0.38	0.89	
c1	.015	.033	0.38	0.84	
D	.776	.815	19.71	20.70	4
D1	.515	-	13.08	-	5
D2	.020	.053	0.51	1.35	
E	.602	.625	15.29	15.87	4
E1	.530	-	13.46	-	
E2	.178	.216	4.52	5.49	
e	.215 BSC		5.46 BSC		
Øk	.010		0.25		
L	.559	.634	14.20	16.10	
L1	.146	.169	3.71	4.29	
ØP	.140	.144	3.56	3.66	
ØP1	-	.291	-	7.39	
Q	.209	.224	5.31	5.69	
S	.217 BSC		5.51 BSC		

LEAD ASSIGNMENTS

HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

IGBTs, CoPACK

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

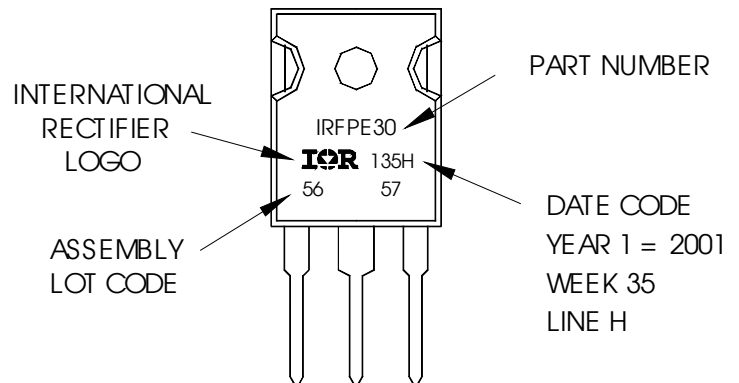
DIODES

- 1.- ANODE/OPEN
- 2.- CATHODE
- 3.- ANODE

TO-247AC Part Marking Information

EXAMPLE: THIS IS AN IRFPE30
WITH ASSEMBLY
LOT CODE 5657
ASSEMBLED ON WW 35, 2001
IN THE ASSEMBLY LINE "H"

Note: "P" in assembly line position
indicates "Lead-Free"



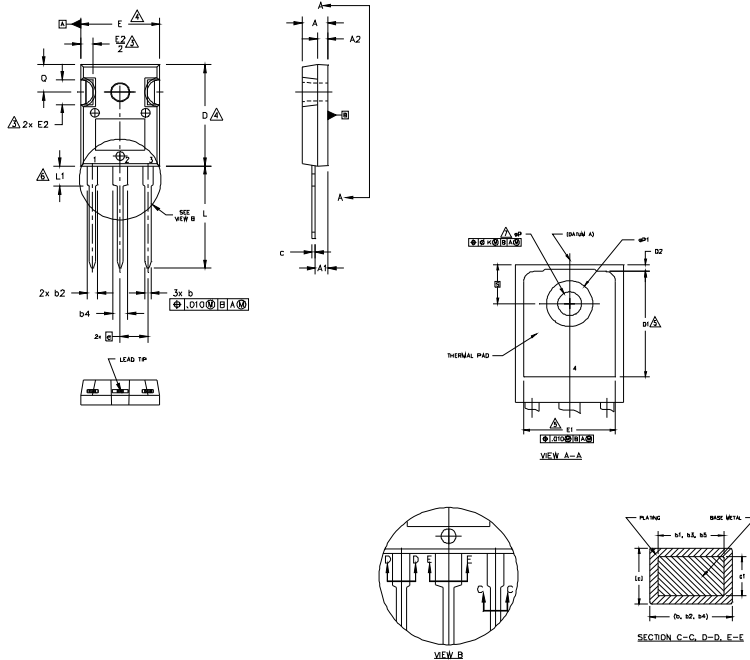
TO-247AC package is not recommended for Surface Mount Application.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

IRG7PH42UPbF/IRG7PH42U-EP

TO-247AD Package Outline

Dimensions are shown in millimeters (inches)



- NOTES:
1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M 1994.
 2. DIMENSIONS ARE SHOWN IN INCHES.
 3. CONTOUR OF SLOT OPTIONAL.
 4. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 5. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS D1 & E1.
 6. LEAD FINISH UNCONTROLLED IN L1.
 7. ϕP TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5 ° TO THE TOP OF THE PART WITH A MAXIMUM HOLE DIAMETER OF .154 INCH.
 8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-247AD.

SYMBOL	DIMENSIONS				NOTES
	INCHES		MILLIMETERS		
	MIN.	MAX.	MIN.	MAX.	
A	.183	.209	4.65	5.31	
A1	.087	.102	2.21	2.59	
A2	.059	.098	1.50	2.49	
b	.039	.055	0.99	1.40	
b1	.039	.053	0.99	1.35	
b2	.065	.094	1.65	2.39	
b3	.065	.092	1.65	2.34	
b4	.102	.135	2.59	3.43	
b5	.102	.133	2.59	3.38	
c	.015	.035	0.38	0.89	
c1	.015	.033	0.38	0.84	
D	.776	.815	19.71	20.70	4
D1	.515	-	13.08	-	5
D2	.020	.053	0.51	1.35	
E	.602	.625	15.29	15.87	4
E1	.530	-	13.46	-	
E2	.178	.216	4.52	5.49	
e	.215 BSC		5.46 BSC		
ϕk	.010		0.25		
L	.780	.827	19.57	21.00	
L1	.146	.169	3.71	4.29	
ϕP	.140	.144	3.56	3.66	
$\phi P1$	-	.291	-	7.39	
Q	.209	.224	5.31	5.69	
S	.217 BSC		5.51 BSC		

LEAD ASSIGNMENTS

HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

IGBTs, CoPACK

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

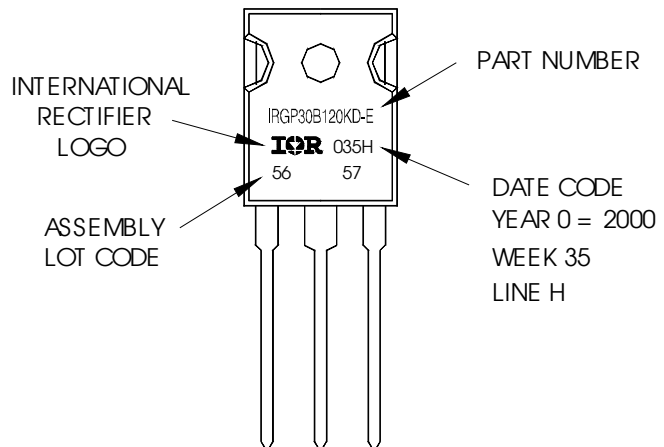
DIODES

- 1.- ANODE/OPEN
- 2.- CATHODE
- 3.- ANODE

TO-247AD Part Marking Information

EXAMPLE: THIS IS AN IRGP30B120KD-E
WITH ASSEMBLY
LOT CODE 5657
ASSEMBLED ON WW 35, 2000
IN THE ASSEMBLY LINE "H"

Note: "P" in assembly line position indicates "Lead-Free"



TO-247AD package is not recommended for Surface Mount Application.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

Data and specifications subject to change without notice.
This product has been designed and qualified for Industrial market.
Qualification Standards can be found on IR's Web site.

OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we stricly control the quality of products and services. Welcome your RFQ to

Email: Info@DiGi-Electronics.com



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.